



THE INSTITUTION OF ENGINEERS, MALAYSIA

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PROFESSIONAL INTERVIEW WORKSHOP (Organised by the Professional Interview Board, IEM)

BEM Approved
PDP Hours: 3
IEM13 /HQ /PDF /003/W

Date : 8 June 2013 (Saturday)
Time : 9.30 am to 12.00 noon (Refreshment will be served at 9.00 am)
Venue : Tan Sri Prof. Chin Fung Kee Auditorium, 3rd Floor, Wisma IEM, Petaling Jaya
Speakers : Ir. Ishak bin Abdul Rahman (Civil)
Ir. Lim Boon Chong (Electrical / Electronic)
Ir. Noor Hisham bin Yahaya (Mechanical)
Ir. Juares Rizal bin Abdul Hamid (Chemical / Others)

REGISTRATION FEE		
Grade	Normal	Online
IEM member	RM30	RM20
Non IEM member	RM120	RM100

The workshop will cover the following:

- Purpose of Professional Interview
- Guidelines for Professional Interview
- Presentation at the Interview
 - Submission of Reports
 - Oral Interview
 - Essay writing
- Code of Ethics



The workshop is to serve as a clarification session for “would-be” Corporate Members. All graduate members with more than 3 years experience are encouraged to attend the workshop and to apply for the Professional Interview thereafter. Members who are interested to participate are requested to return the reply slip to the IEM Secretariat by **31 May 2013** (OFFLINE REGISTRATION) together with the commitment fee payable to *The Institution of Engineers, Malaysia*. Please note that the **commitment fee must be settled prior to the workshop.**

Ir. Hoo Choon Sean
Chairman
Professional Interview Board

Reply Slip (Fax to: 03- 7957 7678 / 03-7958 5453)

Chairman
Professional Interview Board
The Institution of Engineers, Malaysia

PROFESSIONAL INTERVIEW WORKSHOP

I wish to participate in the Professional Interview workshop on **8 June 2013 (Saturday)**. I enclose herewith a cheque No./Cash..... for the amount of..... as my commitment fee for the workshop.

Name of Member:

M'ship No:

Address:

Grade:

.....

Email:

.....

Tel (H/P):

Company's Name:

I/C No. of Participant:

.....

Signature

.....

Date

(Photostat copies are acceptable)